



11-05-03

MEMC 2987
TP-00-2950
PATENT

2818
Image.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of Kan-Yin Ng et al. Art Unit 2818
Serial No. 09/970,404
Filed October 3, 2001
Confirmation No. 9398
For APPARATUS AND PROCESS FOR PRODUCING POLISHED SEMICONDUCTOR
WAFERS
Examiner Phuc T. Dang

November 4, 2003

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop Non-Fee Amendment
TO THE COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

SIR:

This letter is in response to the Office action dated October 9, 2003, in which a restriction of inventions was requested under 35 U.S.C. § 121. The Office action sets forth a restriction requirement to one of the following inventions: Group I, Claims (1-7), drawn to a process of forming a semiconductor wafer which inhibits the formation of surface features on a polished front side of the wafer or Group II, Claims (8-18), directed to an apparatus for wax mounting a semiconductor wafer on a polishing block in preparation for polishing a front side of the wafer.

The Applicants hereby elect Group I, Claims (1-7), without traverse, for further prosecution in the present application. Applicants reserve the right to file a divisional application directed to the non-elected Group II Claims (8-18) at a later date.

Respectfully submitted,

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